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**TITLE:** IC PACKAGE FOR SOLDERLESS MOUNTING  
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**INVENTOR-INFORMATION:**

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**ASSIGNEE-INFORMATION:**

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NEC CORP N/A

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**ABSTRACT:**

**PURPOSE:** To upgrade the efficiency of replacing an IC such as ROM and to reduce product cost by making a mounting board for IC package have a structure that a lead and the corresponding through hole apply a pressure to each other when loading the board with the IC package.

**CONSTITUTION:** Leads 2 are extended vertically from the bottom surface of an IC package so as not to be broken by a friction force when inserting leads 2 in to through holes of a mounting board 4. This lead 2 is made of elastic material, while a section for a through hole 3 on a mounting board 4 has a contact portion 2a slightly larger than the inner diameter of through hole 3 and in the center portion thereof is provided with a hole 2b. Therefore, when inserting the lead 2 in the through hole 3, the contact portion 2a is compressed and thrusted to the inner wall of through hole 3, thereby being able to secure electric and mechanical connection between them.

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